Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1Y**
2. **1A**
3. **1B**
4. **2Y**
5. **2A**
6. **2B**
7. **GND**
8. **3A**
9. **3B**
10. **3Y**
11. **4A**
12. **4B**
13. **4Y**
14. **VCC**

**.044”**

**1 14 13**

**2**

**3**

**4**

**5**

**6 7 8**

**12**

**11**

**10**

**9**

**MASK REF**

**LS**

**0**

**2**

**E**

**.050”**

**Top Material: Al**

**Backside Material: SiNi**

**Bond Pad Size: .004” X .004”**

**Backside Potential: GND**

**Mask Ref: LS 02 E**

**APPROVED BY: DK DIE SIZE .044” X .050” DATE: 7/1/16**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54LS02**

**DG 10.1.2**

#### Rev B, 7/19/02